



Material Content Data Sheet

Item	Material Group	Materials	CAS Number	Mass (gm)	Average Mass (%)	Cumulative Mass (%)	Traces
Part Number Date ROHS Compliant Revision		CCS050M12CM2 4/4/2013 Yes 1.0					
Base Plate Including Metallization	Non Noble Metal Non Noble Metal	Copper Nickel	7440-50-8 7440-02-0	120.20	61.44%	61.4%	x
Substrate Including Metallization	Inorganic Material Non Noble Metal Non Noble Metal	Aluminum Nitride Copper Nickel	24304-00-5 7440-50-8 7440-02-0	10.79	5.52%	66.95%	x x
Chip Including Metallization	Inorganic Material Non Noble Metal Non Noble Metal Noble Metal	Silicon Carbide Aluminum Nickel Silver	409-21-2 7429-90-5 7440-02-0 7440-22-4	0.25	0.13%	67.08%	x x x
Solders	Non Noble Metal + Noble Metal Non noble metal Non noble metal Noble Metal	Alloy Tin Copper Silver	7440-31-5 7440-50-8 7440-22-4	2.65	1.35%	68.44%	x x x
Wire Bonds	Non Noble Metal	Aluminum	7429-90-5	0.30	0.15%	68.59%	
Housing Including Metal Bushing	Inorganic Material Inorganic Material	PBT Fiber Glass	24968-12-5 65997-17-3	39.90	20.39%	88.98%	x
Encapsulation	Polymers	Silicone Gel/Rubber	63394-02-5	15.80	8.08%	97.06%	
Terminal Including Plating	Non Noble Metal Non Noble Metal	Copper Nickel	7440-50-8 7440-02-0	5.73	2.93%	99.99%	x
NTC Thermistor	Inorganic Material + Non Noble Metal + Noble Metal Inorganic Material Inorganic Material Inorganic Material Inorganic Material Inorganic Material Non Noble Metal Non Noble Metal Non Noble Metal Non Noble Metal Noble Metal	Glass Manganese Dioxide Nickel monoxide Copper oxide Butyldiglycol Zinc oxide Iron Tin Copper Nickel Silver	99439-28-8 1313-13-19 1313-99-1 1317-39-1 112-34-5 1314-13-2 7439-89-6 7440-31-5 7440-50-8 7440-02-0 7440-22-4	0.03	0.01%	100.00%	x x x x x x x x x x x
Total Mass (grams)				195.65	100.0%		

NOTES

1. All or part of this material declaration is based on information provided by third parties and/or external testing. Cree reasonably believes this information is complete and accurate, but no warranty is provided with respect to this information.
2. This information is based on information currently available to Cree and is subject to change without prior notice.